

ABSTRACT

A heat resistant film comprising total 100 parts by weight of a resin composition comprising at least (A-1) a polyetherimide resin having repeating units of the structural formula (1), (A-2) a polyetherimide resin having repeating units of the structural formula (2), and (B) a polyarylnketone resin having a melting peak temperature of 260 degrees C or higher, and 5 to 50 parts by weight of a filler, wherein a weight ratio of the resin components, [(A-1) + (A-2)] / (B), ranges from 70/30 to 30/70 and a weight ratio, (A-1) / (A-2), ranges from 70/30 to 30/70.

